



International Conference and Exhibition
on Integration Issues of Miniaturized Systems

Amsterdam, The Netherlands,
13–14 March 2013

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Why to attend

It is the **International Conference and Exhibition** on integration of materials, devices and systems. Starting 2007 as European Conference and Exhibition it has meanwhile become a leading event at international level. SSI serves as communication platform for academia, research and industry to exchange know-how on smart systems integration.

The event features application-oriented as well as scientific sessions and addresses the complete value-added chain of smart systems. Moreover an overview of special European programs focusing on smart systems integration is given.

The 2012 edition in Zurich was attended by more than 300 experts from 25 countries.

Who should attend

The event targets researchers, developers and users in equal measure. It is the platform for smart systems integration experts and managers from the automation, automotive, aerospace, telecommunication, medical technology, logistics, RFID and life science industry sectors.

At a glance

Register in advance!

Registration starts mid January 2013.

Early bird prices are available until 08 February 2013.



Smart Systems Integration 2013 will be once again co-located with MEMS Executive Congress Europe held at the Steigenberger Airport Hotel Amsterdam on 12 March 2013. 20% discount on the regular conference rate will be granted to the delegates of the corresponding partner event.

Program and registration at
www.smartsystemsintegration.com

Venue

Park Plaza Hotel Amsterdam Airport
Melbournestraat 1
1175 RM Lijnden, the Netherlands
www.parkplaza.com



Organizer



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Highlights 2013

Main conference topics

- 3D-Integration and system packaging
- Manufacturing technologies for smart integrated systems
- Smart medtech systems and systems for prognostics health management

Keynotes by

- **Carmelo Papa**, EPoSS and STMicroelectronics, I
- **Khalil Rouhana**, European Commission, B
- **Prof. Dr. Jaap den Toonder**, Philips Research, NL
- **Michael Fink**, Micro Systems Technologies, CH
- **Brian Wirth**, GE Sensing & Inspection Technologies, USA

Further highlights

- Pre conference field trip to the European Space Agency
- Special sessions by EPoSS
- Special US-session
- Accompanying exhibition
- Conference dinner including channel cruise
- Co-location with MEMS Executive Congress Europe

